

Tin MBF 20

Tin MBF 20 is a strongly acidic, fluoride-free process for the deposition of silky-matt fine crystalline coatings. It is used for tin plating of wires and tapes in reel-to-reel plating lines. The additives used are low foaming and so during operation no disturbing foam formation occurs. The deposits from Tin MBF 20 give excellent solderability and melting behaviour in reflow processes even after heat ageing (e.g. 155 °C / 16 hours).

The information in this data sheet is based on laboratory as well as practical experience. Figures quoted for operating limits and replenishment quantities are for guidance. Actual values necessary will depend on the components being plated (material and geometry), their application and plating plant conditions.

Important:

Please read this instruction carefully prior to the use of the process and carefully follow all the parameters that have a direct influence on the operation. We reserve the right to make technical changes. In the interest of safety, please pay attention to the hazard warnings on the labels of the containers. The minimum shelf life of the products is included on the labels and is also available in the appropriate Quality Assurance (QA03).

The current IMDS number of the layer deposited from the process is available on the internet at www.schloetter.com/downloads.

For the storage of chemical products the TRGS 510 must be followed.

If the additives used in this process contain a SVHC-substance, then this will be specified in the corresponding Material Safety Data Sheet, section 15.

